

# SOT904-1

plastic thin fine-pitch ball grid array package; 84 balls; body  
7 x 7 x 0.8 mm

8 February 2016

Package information

## 1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA84
Package type industry code	TFBGA84
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-195
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	9-6-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		6.9	-	7	7.1	mm
E	package width		6.9	-	7	7.1	mm
A	seated height		[tbd]	-	1.1	1.1	mm
A <sub>2</sub>	package height		0.75	-	0.8	0.85	mm
n <sub>2</sub>	actual quantity of termination		-	-	84	-	



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2. Package outline

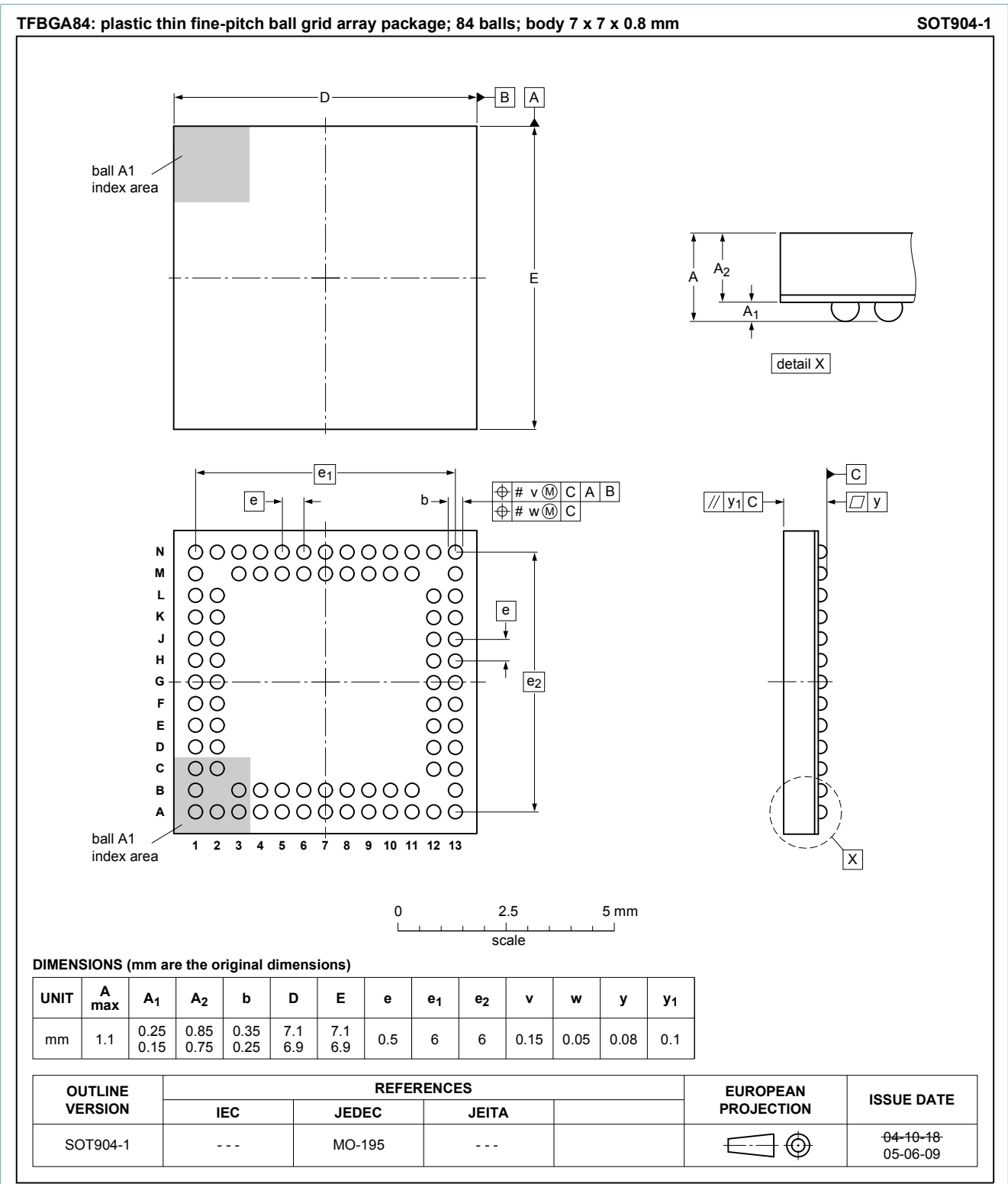


Fig. 1. Package outline TFBGA84 (SOT904-1)

### 3. Legal information

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